Anaren

RF Power

Model RFP-250-100RM

Flanged Resistors
250 Watts, 100 Ω

勝 特 力 材 料 886-3-5753170
胜特力电子(上海) 86-21-34970699
胜特力电子(深圳) 86-755-83298787
Http://www.100y.com.tw

General Specifications

Resistive Element:	Thick film
Substrate:	Beryllium oxide ceramic
Cover:	Alumina ceramic
Mounting Flange:	Copper, nickel plated per QQ-N-290
Lead(s):	99.99% pure silver (.005" thk)

Features

- DC - 2.0 GHz
- 250 Watts
- BeO Ceramic
- Welded Silver Leads
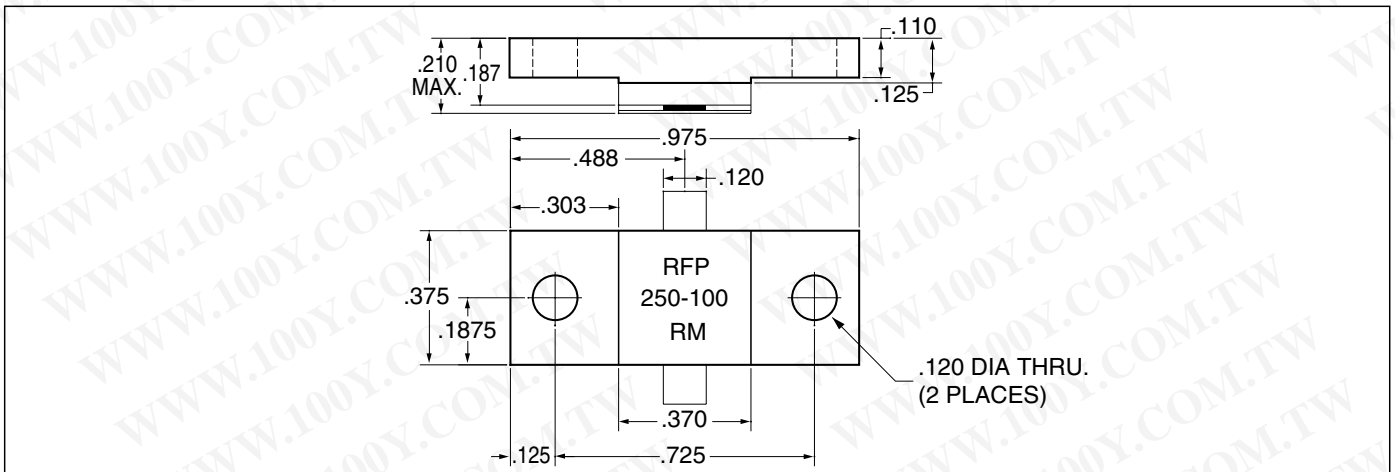- Non-Nichrome Resistive Element
- 100% Tested

Electrical Specifications

Resistance Value:	100 ohms, ±5%
Frequency Range:	DC - 2.0 GHz
Power:	250 Watts
Capacitance:	3.3 pF

Notes: Tolerance is ±.010, unless otherwise specified. Operating temperature is -55°C to +150°C (see chart). Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions are in inches. Lead length 0.15" minimum.
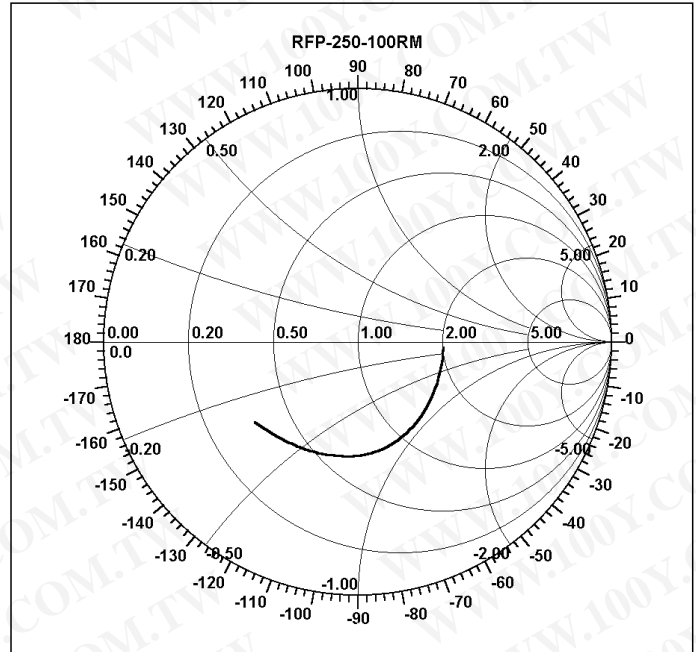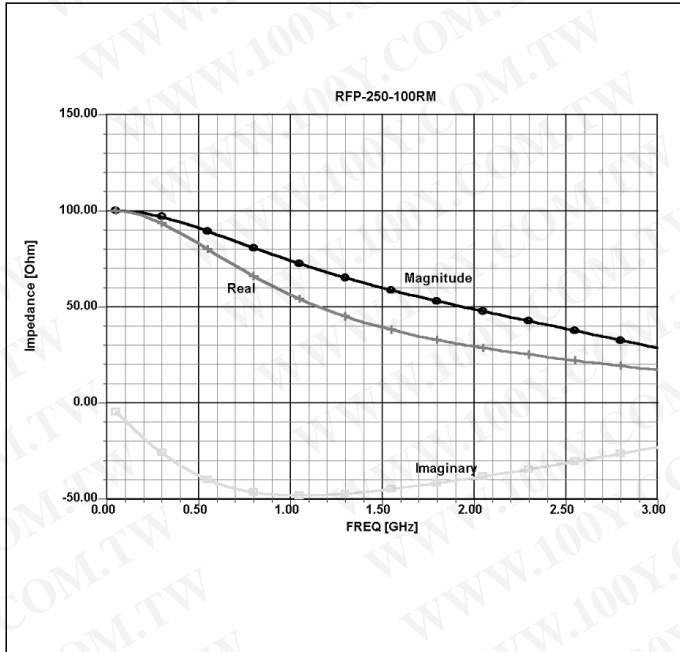**Specifications subject to change without notice.**

Outline Drawing

.210 MAX. .187   .110   .125

.975
.488   .120
.303

RFP 250-100 RM

.375   .1875

.120 DIA THRU. (2 PLACES)

.370
.125   .725

VER. 12/5/01

Sales Desk USA: Voice: **(800) 544-2414** Fax: **(315) 432-9121**
Sales Desk Europe: Voice: **(+44) 23 92 232392** Fax: **(+44) 23 92 251369**

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What'll we think of next?™

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Typical Performance

RFP-250-100RM

RFP-250-100RM

Power Derating
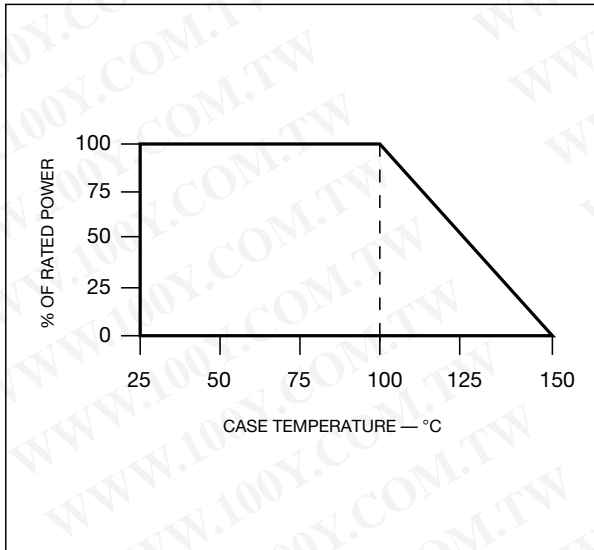
Suggested Mounting Procedures

.025 MIN.
(2 PLACES)

BOARD LOWER THAN LEAD.   BOARD EVEN WITH LEAD.   BOARD LOWER THAN LEAD.   BOARD HIGHER THAN LEAD.

SUGGESTED STRESS RELIEF METHODS   NOT RECOMMENDED APPLICATION

SCALE: SCALE:

1. Make sure that the devices are mounted on flat surfaces (.001" under the device) to optimize the heat transfer.

2. Drill & tap the heatsink for the appropriate thread size to be used.

3. Coat heatsink with a minimum amount of high quality silicone grease (.001" max. thickness).

4. Position device on mounting surface and secure using socket head screws, flat & split washers. Torque screws to the appropriate value. Make sure that the device is flat against the heatsink. (Care should be taken to avoid upward pressure of the leads towards the lid).

5. Solder leads in place using an SN63 type solder with a controlled temperature iron (210°C).

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